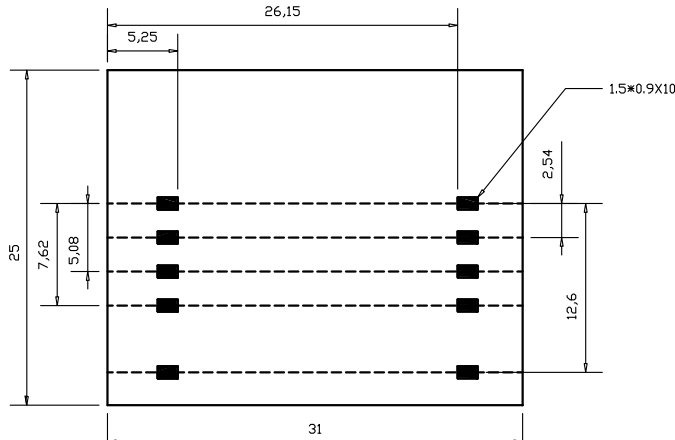
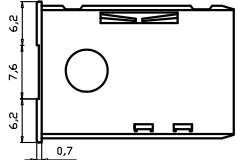
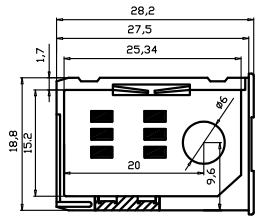


REV.	ECN.NO.	APPD.
A	XXXXXXXXXX	chenyiting

盖板(抽屉)尺寸

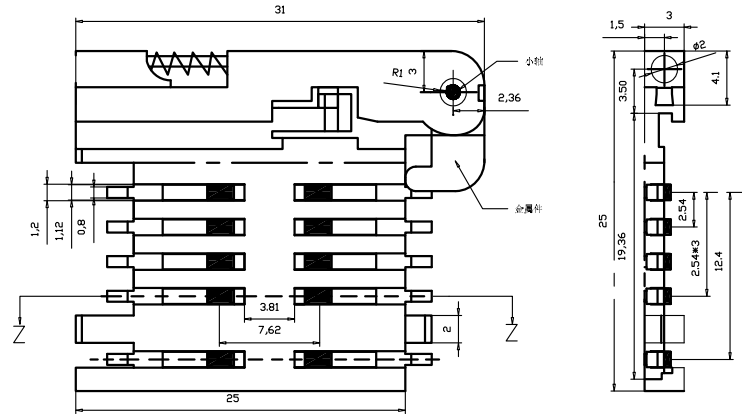


RECOMMENDED PCB LAYOUT



- *Electrical Characteristics:
Contact Current Rating:0.5 Amperes.
Dielectric Withstanding Voltage:AC500V r.m.s.
Insulation Resistance:1000 MΩ Minimum.
Contact Resistance:100 mΩ Maximum.
- *Environmental:
Operating Temperature:-25°C~+90°C.
- *Environmental:
Mating Cycles:5000~10,000 Insertions.
- *Mechanical Characteristics:
Card Push Insertion/Out Force:1.4kgf. MAX
Contact Separation Force:0.20kgf Minimum.
- *Material:
Insulator:HI-Temp Plastic UL 94V-0 Rated.
Contact:Copper Alloy(t=0.15mm).
Shell:Stainless Steel(t=0.20mm).
Spring:SWP.

SD5209-051-G618
G:半金G/Fu”
1:黑色
6:LCP



TOLERANCE UNLESS OTHERWISE SPECIFIED		HLW 深圳市华联威电子科技有限公司					
.XXX ±0.10		.X' ±3"		HUA LIAN WEI TECHNOLOGY ELECTRONICS CO;LTD.			
.XX ±0.20		.XX' ±2"		APPROVED	PART NAME:	SIM抽屉式卡座连接器卡座全塑SIM卡座全塑6P车载GPS卡座	
.X ±0.30				CHECKED	PART No:	SD5209-051-G618	C
DRAWN	chenyiting	PROJECTION:	UNIT:	SCALE	SHEET	REV.	
DATE	2023.04.17		mm	1:1	10F1	A	